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April 2016

HUFA76407DK8T_F085

Dual N-Channel Logic Level UltraFET Power MOSFET 60 V, 3.5 A, 105 m Ω

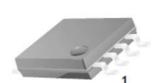
General Description

These N-Channel power MOSFETs are manufactured using the innovative UltraFET® process. This advanced process technology achieves the lowest possible onresistance per silicon area, resulting in outstanding performance. This device is capable of withstanding high energy

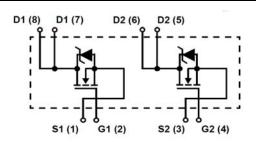
in the avalanche mode and the diode exhibits very low reverse recovery time and stored charge. It was designed for use in applications where power efficiency is important, such as switching regulators, switching convertors, motor drivers, relay drivers, low-voltage bus switches, and power management in portable and battery-operated products.

Features

- Ultra-Low On-Resistance $r_{DS(on)}$ = 0.090 Ω at V_{GS} = 10 V
- Ultra-Low On-Resistance $r_{DS(on)} = 0.105\Omega$ at $V_{GS} = 5$ V
- Peak Current vs Pulse Width Curve
- UIS Rating Curve
- Transient Thermal Impedance Curve vs Board Mounting Area
- Switching Time vs R_{GS} Curves
- Qualified to AEC Q101
- RoHS Compliant



SO-8



MOSFET Maximum Ratings T_A = 25 °C unless otherwise noted

Symbol	Parameter	Ratings	Units	
V_{DSS}	Drain to Source Voltage (Note 1)	60	V	
V_{DRG}	Drain to Gate Voltage ($R_{GS} = 20k\Omega$) (Note 1)	60	V	
V_{GS}	Gate to Source Voltage	±16	V	
I _D	Drain Current -Continuous (T _A = 25 °C, V _{GS} = 5V) (Note 2)	3.5		
	-Continuous ($T_A = 25$ °C, $V_{GS} = 10V$) (Figure 2) (Note 2)	3.8	^	
	-Continuous ($T_A = 100 ^{\circ}\text{C}, V_{GS} = 5\text{V}$) (Note 3)	1	Α	
	-Continuous ($T_A = 100 ^{\circ}\text{C}$, $V_{GS} = 4.5\text{V}$) (Figure 2) (Note 3)	1		
I _{DM}	Drain Current -Pulsed	Figure 4		
UIS	Pulsed Avalanche Rating	Figures 6, 17, 18		
D	Power Dissipation (Note 2)	2.5	W	
P_{D}	Derate Above 25 °C	20	mW/°C	
T _J , T _{STG}	Operating and Storage Junction Temperature Range	-55 to +150	°C	
T_L	Temperature for Soldering - Leads at 0.063in (1.6mm) from Case for 10s	300	°C	
T _{pkg}	Temperature for Soldering - Package Body for 10s, See Techbrief TB334	260	°C	

Package Marking and Ordering Information

76407DK8 HUFA76407DK8T F085 SO-8 330mm 12mm 2500 unit	Device Marking	Device	Package	Reel Size	Tape Width	Quantity
70 107 B10 107 B101 _ 1 000	76407DK8	HUFA76407DK8T_F085	SO-8	330mm	12mm	2500 units

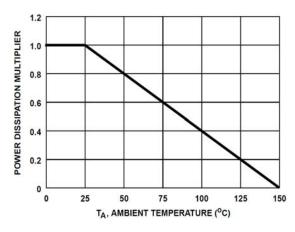
Notes:

- 1. T_J = 25 °C to 125 °C.
- 2. 50°C/W measured using FR-4 board with 0.76 in² (490.3 mm²) copper pad at 1second.
- 3. 228°C/W measured using FR-4 board with 0.006 in² (3.87 mm²) copper pad at 1000 seconds.
- 4. A suffix as "...F085P" has been temporarily introduced in order to manage a double source strategy as Fairchild has officially announced in Aug 2014.

Electrical Characteristics T_J = 25°C unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units	
Off Chara	ecteristics						
		I _D = 250 μA (Figure 12)	60	-	-	.,	
BV _{DSS}	Drain to Source Breakdown Voltage	$V_{GS} = 0 \text{ V}$ $T_A = -40 \text{ °C(Figure 12)}$	55	-	-	V	
	Zoro Cata Valtaga Drain Current	V _{DS} = 55 V,	-	-	1		
IDSS	Zero Gate Voltage Drain Current	V _{GS} = 0 V T _A = 150 °C		-	250	μΑ	
I_{GSS}	Gate to Source Leakage Current	V _{GS} = ±16 V	-	-	±100	nA	
On Chara	cteristics						
V _{GS(th)}	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_D = 250 \mu\text{A} \text{ (Figure 11)}$	1	-	3	V	
00()	Static Drain to Source On Resistance	I _D = 3.8 A, V _{GS} = 10 V (Figure 9,10)	-	0.075	0.090		
r _{DS(on)}		$I_D = 1.0 \text{ A}, V_{GS} = 5 \text{ V}$ (Figure 9)	-	0.088	0.105	Ω	
		I _D = 1.0 A, V _{GS} = 4.5 V (Figure 9)	-	0.092	0.110	-	
Thermal (Characteristics						
	T. 15	0.76in ² (490.3mm ²) Pad (Note 2)	-	-	50	°C/W	
$R_{\theta JA}$	Thermal Resistance Junction to Ambient	0.027in ² (17.4mm ²) Pad (Figure 23)	-	-	191		
	,	0.006in ² (3.87mm ²) Pad (Figure 23)	-	-	228		
Switching	Characteristics (V _{GS} =4.5V)						
t _{on}	Turn-On Time		-	-	57	ns	
t _{d(on)}	Turn-On Delay Time		-	8	-	ns	
t _r	Rise Time	$V_{DD} = 30 \text{ V}, I_D = 1.0 \text{ A},$	-	30	-	ns	
t _{d(off)}	Turn-Off Delay Time	$V_{\rm GS}$ = 4.5 V, R _{GS} = 27 Ω (Figure 15, 21, 22)	-	25	-	ns	
t _f	Fall Time		-	25	-	ns	
t _{off}	Turn-Off Time		-	-	75	ns	
Switching	Characteristics (V _{GS} =10V)						
t _{on}	Turn-On Time		-	-	24	ns	
t _{d(on)}	Turn-On Delay Time		-	5	-	ns	
t _r	Rise Time	$V_{DD} = 30 \text{ V}, I_D = 3.8 \text{ A},$	-	11	-	ns	
t _{d(off)}	Turn-Off Delay Time	V_{GS} = 10 V, R_{GS} = 30 Ω (Figure 16, 21, 22)	-	46	-	ns	
t _f	Fall Time	(Figure 16, 21, 22)	-	31	-	ns	
t_{off}	Turn-Off Time		-	-	116	ns	
Gate Cha	rge Characteristics						
Q _{g(TOT)}	Total Gate Charge	$V_{GS} = 0 \text{ to } 10 \text{ V}$ $V_{DD} = 30 \text{ V},$	-	9.4	11.2	nC	
Q _{g(5)}	Gate Charge at 5V	$V_{GS} = 0 \text{ to } 5 \text{ V}$ $I_{D} = 1.0 \text{ A},$	-	5.3	6.4	nC	
Q _{g(TH)}	Threshold Gate Charge	$V_{GS} = 0 \text{ to } 1 \text{ V}$ $I_{g(REF)} = 1.0 \text{ mA},$	-	0.42	0.5	nC	
Q _{gs}	Gate to Source Charge	(Figure 14, 19, 20)	-	1.05	-	nC	
Q _{gd}	Gate to Drain "Miller" Charge		-	2.4	-	nC	
Dynamic	Characteristics						
C _{iss}	Input Capacitance	V _{DS} = 25 V, V _{GS} = 0 V,	-	330	-	pF	
C _{oss}	Output Capacitance	f = 1MHz,	-	100	-	pF	
C _{rss}	Reverse Transfer Capacitance	(Figure 13)	-	18	-	pF	
Drain-Soເ	urce Diode Characteristics						
	Course to Drain Diada, Farmard Vallana	I _{SD} = 3.8 A	Α		1.25	V	
V_{SD}	Source to Drain Diode Forward Voltage $I_{SD} = 1.0 \text{ A}$		-	-	1.00		
t _{rr}	Reverse Recovery Time	-I _F = 1.0 A, di/dt = 100 A/μs	-	-	48	ns	
Q _{rr}	Reverse Recovery Charge	1F - 1.0 Λ, αναι - 100 Α/μδ	-	-	89	nC	

Typical Characteristics $T_J = 25^{\circ}C$ unless otherwise noted



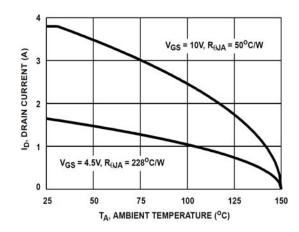


Figure 1. NORMALIZED POWER DISSIPATION vs. AMBIENT TEMPERATURE

Figure 2. MAXIMUM CONTINUOUS DRAIN CURRENT vs. AMBIENT TEMPERATURE

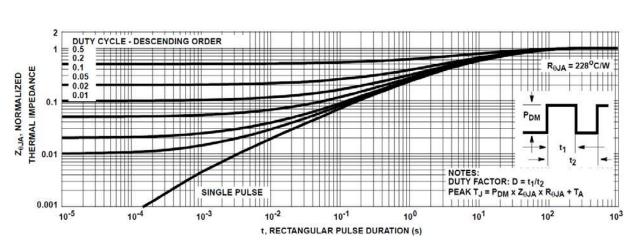


Figure 3. NORMALIZED MAXIMUM TRANSIENT THERMAL IMPEDANCE

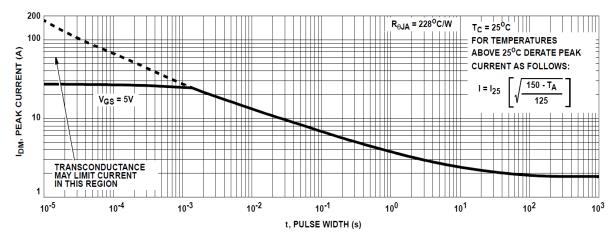


Figure 4. PEAK CURRENT CAPABILITY

Typical Characteristics T_J = 25°C unless otherwise noted

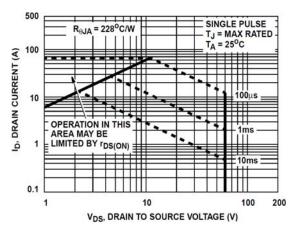


Figure 5. FORWARD BIAS SAFE OPERATING AREA

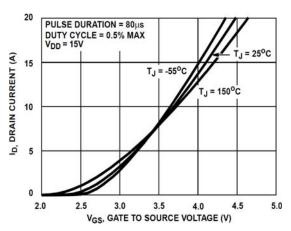


Figure 7. TRANSFER CHARACTERISTICS

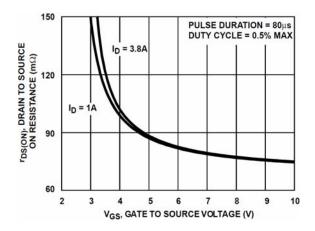


Figure 9. DRAIN TO SOURCE ON RESISTANCE vs GATE VOLTAGE AND DRAIN CURRENT

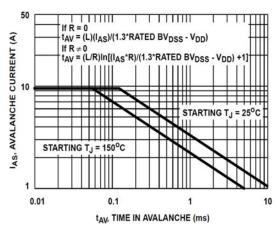


Figure 6. UNCLAMPED INDUCTIVE SWITCHING CAPABILITY

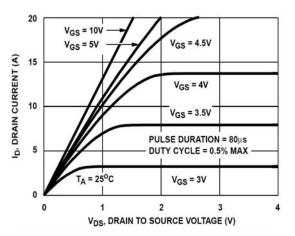


Figure 8. SATURATION CHARACTERISTICS

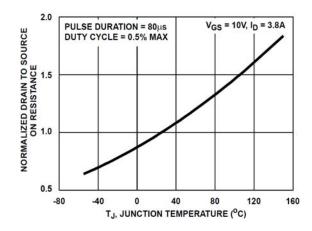


Figure 10. NORMALIZED DRAIN TO SOURCE ON RESISTANCE vs JUNCTION TEMPERATURE

Typical Characteristics T_J = 25°C unless otherwise noted

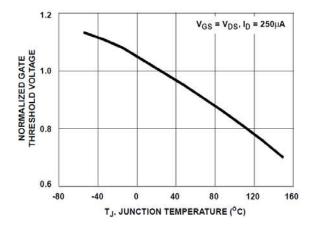


Figure 11. NORMALIZED GATE THRESHOLD VOLTAGE vs JUNCTION TEMPERATURE

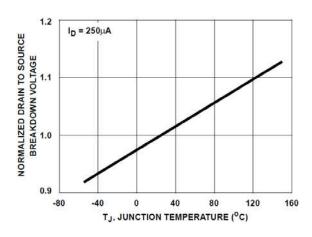


Figure 12. NORMALIZED DRAIN TO SOURCE BREAKDOWN VOLTAGE vs JUNCTION TEMPERATURE

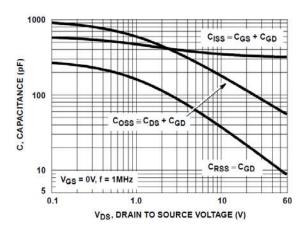


Figure 13. CAPACITANCE vs DRAIN TO SOURCE VOLTAGE

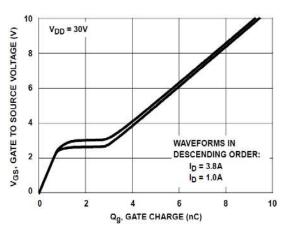


Figure 14. GATE CHARGE WAVEFORMS FOR CONSTANT GATE CURRENT

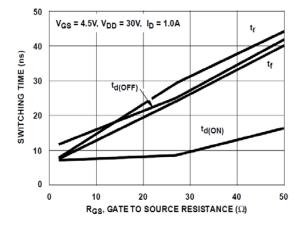


Figure 15. SWITCHING TIME vs GATE RESISTANCE

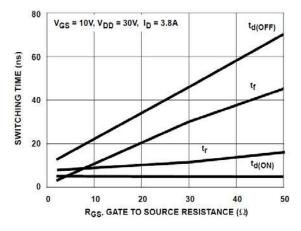
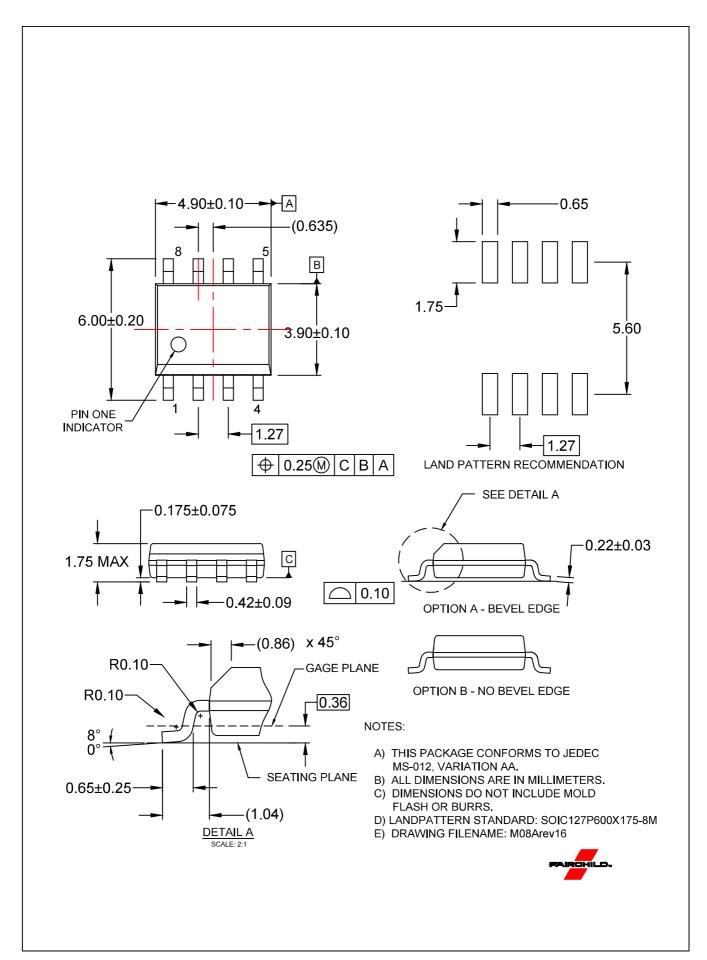


Figure 16. SWITCHING TIME vs GATE RESISTANCE



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